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Authors: Y. Liang, D.G. Liu, W.Q. Bai, J.P. Tu

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Investigation of silicon carbon nitride nanocomposite films as a wear resistant layer in vitro and in vivo for joint replacement applications

Y. Liang^a, D.G. Liu^{b* c}, W.Q. Bai, J.P. Tu^{d*}

^aCenter of Medical Device Adverse Events Monitoring of Anhui, Center for Adverse Drug Reaction Monitoring of Anhui, Hefei, 230031, China

^bSchool of Materials Science and Engineering, Hefei University of Technology, Hefei, 230099, China

^cCenter of Composite Material and Surface Treatment, China Electronic Technology Group Corporation No. 38 Research Institute (CETC 38), Hefei, 230088, China

^dState Key Laboratory of Silicon Materials and Department of Materials Science and Engineering, Zhejiang University, Hangzhou 310027, China

* Corresponding author: Tel: +86-551-65391784; Fax: +86-551-65391790

E-mail address: liudongguang2007@163.com; tujp@zju.edu.cn (J.P. Tu)

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